

09/9/2014

ABSTRACT

A semiconductor chip package is formed by a first semiconductor chip and a second semiconductor chip, which have electrodes for wiring at surfaces thereof, being integrated and mounted in a state in which reverse surfaces thereof oppose one another. Therefore, two semiconductor chips can be freely combined and mounted regardless of chip sizes thereof, and lengths of wires can be shortened. Thus, a wire-bonding yield can be improved, and a semiconductor package having excellent electric characteristics can be obtained.

009204 0294
T09220 49021660